威达诚实业有限公司 WEIDACHENG INDUSYRY CO., LTD

SOLDERING PLACEMENT' SYSTEM

锡球植入机-BU-510

植球能力: 0.4Φ~0.76Φ 植球范围:L-60mm. W-80mm



各类 BGA-植球

真空清除锡球座(清球配

备)





维修设备

锡球植入机

BGA rework equipment --- Solder ball placement system BU-510

(1)外部尺寸 :75cm(L),X 25cm(W),X 26cm(H)

■ Outside dimension: 75cm(L), 25cm(W), 26cm(H).

(2)重 量: 28.7 kg. ■ Weight: 28.7 kg.

(3)使用电压:110/220V 50/60Hz.

■ Working voltage: 110/220V;50/60Hz

(4)使用气压 : 6 kg/cm².

■ Working air pressure: 6 kg/cm².

(5)锡球规格 :依 BGA 不同使用锡球规格而异.

■ Solder ball specification: According to the solder ball spec being used by different kinds of BGA package.

(6)BGA 模具:依BGA不同规格SIZE可更换需求BGA模具.

- BGA IC holder: It is available for changing-over different types of BGA IC holders according to different size or spec of BGA package.
- (7) BGA 模具:依 BGA 不同规格 SIZE 可更换需求锡球模具模具.
 - Solder ball screening fixture: It is available for changing-over different ball screening fixtures according to different size or spec of solder ball.
- (8)锡球植入速度: 锡球植入 BGA-PAD 点可微调控制锡球植入速度.
 - Solder ball placing speed: The speed for placing solder balls onto BGA pads can be adjusted and fine-tuning controlled.
- (9)锡球植入率:百分之98.
 - Ball-placing yield rate: 98%.
- (10)锡球植入精度:0.03 mm.
 - Ball-placing accuracy: 0.03mm.
- (11)模具槽退料:退料速度 30 300 mm/S.
 - BGA IC holder unloading speed: Unloading speed 30~300 mm/s.
- (12)自动植球时间:22/sec
 - Automatic ball-placing operation cycle time : 22 seconds.

BGA 再造

BGA regeneration! 以低廉锡球 重新植入再造完整

~ Place solder balls on BGA to regenerate a whole new one with the lowest cost. ~ 锡球植入机,未拆下 BGA 重新植入全新锡球,以利重新回焊维修,本设备提供 SMT 业界进入 BGA 作业技术层次的提升,本机为 BGA 生产作业得力助手.

The solder ball placement system places new solder balls again onto ball removed BGA-IC for new reflowing rework. This equipment provides a technology promotion for traditional BGA operation in SMT industry. It is a very useful tool for BGA production.

本设备荣获多国专利仿冒必究

[There are patents approved by lots of countries for this equipment. All rights are reserved]